

Bill of Materials

TI DESIGNS

TIDC-BLE-TO-WIFI-IOT-GATEWAY

Item	Quantity	Part Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Package
				ANTENNA, COMPONENT, HIGH				
				FREQUENCY CERAMIC, 50R,	JOHANSON			
1	1	A3	2450AT42B100	2.4GHz-2.5GHz, 1206, SMD	TECHNOLOGY	2450AT42B100	Nil	
				MECHANIC, ANTENNA, 2.45 GHZ,				
			2450AT18D010	DETUNING RESILIENT, EDGE	JOHANSON			
2	1	A3	0	MOUNT, 1206, SMD	TECHNOLOGY	2450AT18D0100E	Nil	1206
2	1	ANT1	105	CAPACITOR, CERAMIC COG/NPO, 1pF, 50V, -0.25pF/ +0.25pF, -	NALIDATA	CDM4555C4114D0C404D	Nil	0402
3	1	ANT1	1pF	55DEGC/+125DEGC, 0402, SMD INDUCTOR, STANDARD, CHIP,	MURATA	GRM1555C1H1R0CA01D	INII	0402
4	1	ANT2	22nH	22nH, -5%/+5%, 0.3A, - 55DEGC/+125DEGC, 0402, SMD	MURATA	LQG15HS22NJ02D	Nil	0402
				RESISTOR, DO NOT MOUNT, 0402,	DO NOT			
5	1	ANT3	DNM	SMD	MOUNT	DNM	Nil	0402
				CAPACITOR, CERAMIC, N/A				
				VALUE, -55DEGC/+125DEGC,	Manufacturer			
6	4	C15 C25 C27 C40	DNM	0402, SMD	selection	CAPACITOR_0402_DNM_N/A_M	Nil	0402

				CAPACITOR, CERAMIC X5R, 1uF,				
				10V, -10%/+10%, -				
7	2	C26 C331	1uF	55DEGC/+85DEGC, 0402, SMD	MURATA	GRM155R61A105KE15D	Nil	0402
				CAPACITOR, CERAMIC X5R, 100nF,				
		C35 C322 C568		10V, -10%/+10%, -	MANUFACTURE	CAPACITOR_0201_100nF_X5R_I_		
8	5	C576	100nF	55DEGC/+85DEGC, 0201, SMD	R SELECTION		Nil	0201
						_		
				CAPACITOR, CERAMIC COG/NPO,				
				12pF, 50V, -5%/+5%, -	MANUFACTURE	CAPACITOR_0402_12pF_C0G/NP		
9	2	C36 C38	12pF	55DEGC/+125DEGC, 0402, SMD	R SELECTION	0_M_+/-5%_50V	Nil	0402
		C91 C101 C111						
		C191 C241 C251						
		C271 C281 C321		CAPACITOR, CERAMIC X7R, 100nF,				
		C361 C382 C491		6.3V, -10%/+10%, -				
10	14	C541 C561	100nF	55DEGC/+125DEGC, 0402, SMD	MURATA	GRM155R70J104KA01D	Nil	0402
				CAPACITOR, CERAMIC, X5R, 10uF,				
		C99 C564 C565		4V, -20%/+20%, -				
11	5	C566 C567	10uF	55DEGC/+85DEGC, 0402, SMD	TDK	C1005X5R0G106M050BB	Nil	0402
				CAPACITOR, CERAMIC X5R, 10uF,				
		C192 C432 C471		6.3V, -20%/+20%, -				
12	5	C481 C574	10uF	55DEGC/+85DEGC, 0603, SMD	MURATA	GRM188R60J106ME47D	Nil	0603
				CAPACITOR, CERAMIC COG/NPO,				
				6.2pF, 50V, -0.25pF/+0.25pF, -				
13	2	C221 C231	6.2pF	55DEGC/+125DEGC, 0402, SMD	MURATA	GRM1555C1H6R2CA01D	Nil	0402
				CAPACITOR, CERAMIC COG/NPO,				
				10pF, 50V, -5%/+5%, -				
14	1	C311	10pF	55DEGC/+125DEGC, 0402, SMD	MURATA	GRM1555C1H100JA01D	Nil	0402
				CAPACITOR, CERAMIC X5R, 4.7uF,				
		C371 C391 C441		6.3V, -20%/+20%, -				
15	4	C562	4.7uF	55DEGC/+85DEGC, 0402, SMD	MURATA	GRM155R60J475ME87D	Nil	0402

				CAPACITOR, CERAMIC X5R, 22uF,				
				4V, -20%/+20%, -				
16	2	C421 C422	22uF	55DEGC/+85DEGC, 0603, SMD	MURATA	GRM188R60G226MEA0D	Nil	0603
				CAPACITOR, CERAMIC COG/NPO,				
				22pF, 50V, -5%/+5%, -				
17	2	C511 C521	22pF	55DEGC/+125DEGC, 0402, SMD	MURATA	GRM1555C1H220JA01D	Nil	0402
				CAPACITOR, CERAMIC RADIO				
				FREQUENCY AND MICROWAVE,				
				15pF, -1%/+1%, NPO, 200V, 0402,				
18	1	C563	15pF	SMD	ATC CERAMICS	600L150FT200T	Nil	0402
				OPTO, LED, SUPER RED COLOR,				
				630nm, 1.8V TO 2.3V, 0.06A,				
19	1	CR1	LS L296-P2Q2-1	0603, SMD	OSRAM	LS L296-P2Q2-1-Z	Nil	0603
				OPTO, LED, GREEN COLOR,				
20	1	CR2	LPL296-J2L2-25	562nm, 0.02A, 0.08W, 0603, SMD	OSRAM	LP L296-J2L2-25	Nil	0603
				DIODE, PROTECTION, ESD ARRAY,				
				2 CHANNEL, 7V, -	TEXAS			
21	1	CR4	TPD2EUSB30DR	40DEGC/+85DEGC, SOT3, SMD	INSTRUMENTS	TPD2EUSB30DRTR	Nil	SOT3
			DEA202450BT-	, , ,				
22	1	FL1	1294C1	-40DEGC/+85DEGC, SMD	TDK	DEA202450BT-1294C1	Nil	
				FILTER, LC, BAND PASS				
	_			FILTER@50R, 2450MHz, -				
23	1	FL2	LFB182G	40DEGC/+85DEGC, 0603, SMD	MURATA	LFB182G45BG2D280	Nil	0603
		F . 0	BLM18HE152SN	FILTER, EMI, 1500@100MHz, -		B1 4 4 6 1 5 1 5 2 2 2 2 2 2		0.000
24	1	FL3	1	55DEGC/+125DEGC, 0603, SMD	MURATA	BLM18HE152SN1D	Nil	0603
				CONNECTOR COAY DE FENANCE				
25	2	14.12	NAC AECUE	CONNECTOR, COAX RF, FEMALE,	LUDOCE	NAC 45CH5	NI:I	
25	2	J1 J2	MS-156HF	STRAIGHT, 2 PINS, SMD	HIROSE	MS-156HF	Nil	

				CONNECTOR, MICRO-USB, 1 ROW,				
26	1	J3	47491-0001	5 PINS, PITCH 0.65mm, SMD	MOLEX	47491-0001	Nil	
20		15	47431 0001	INDUCTOR, CHIP, 2.2uH, -	WIOLEX	47431 0001	1411	
				20%/+20%, 1.2A, -				
27	2	L381 L431	2.2uH	55DEGC/+125DEGC, 0806, SMD	MURATA	LQM2MPN2R2MG0L	Nil	0806
27		L301 L431	2.2011	INDUCTOR, CHIP, 1uH, -	WIONATA	EQIVIZIVII INZINZIVIGUE	1111	0000
				20%/+20%, 1.5A, -				
28	1	L401	1uH	55DEGC/+125DEGC, 1008, SMD	MURATA	LQM2HPN1R0MJ0L	Nil	1008
20		L401	Tuii	INDUCTOR, CHIP,	WORATA	EQIVIZITENTINOIVIJOE	INII	1008
				1000hm@100MHz , -25%/+25%,	SAMSUNG			
				0.6A, -55DEGC/+125DEGC, 0603,	ELECTRO-			
29	1	L474	CIM10U800N	SMD	MECHANICS	CIM10U800NC	Nil	0603
25	т	L4/4	CINITOOSOON	INDUCTOR, CHIP, 10uH, -	IVIECHAINICS	CIMITOOSOOMC	INII	0003
				20%/+20%, 0.11A, -				
30	1	L475	10uH	40DEGC/+85DEGC, 0805, SMD	TAIYO YUDEN	CKS2125100M-T	Nil	0805
30		L475	1000	NON COMPONENT, CONNECTOR	TAITO TODEN	CR32125100IVI-1	INII	0803
				· · · · · · · · · · · · · · · · · · ·				
21	2	P4 P5	TC2030-CTX-NL	CABLE, PLUG OF NAILS, 6 PINS, 2 ROWS, SMD				
31		P4 P5	TC2U3U-CTX-INL	,				
				TRANSISTOR, MOSFET N-	TEVAC			
22	4	0.1	CCD42204F4	CHANNEL, 12V, 2.1A, 0.5W, LGA3,	TEXAS	CCD4220454	NI:1	1643
32	1	Q1	CSD13381F4	SMD	INSTRUMENTS	CSD13381F4	Nil	LGA3
		D40 D24 D22 D24		RESISTOR, THICK FILM, 270R, -				
22	6	R10 R21 R22 R24	270	5%/+5%, 0.05W, 30V, -	\/(C A\/	CDC/M/0204270DINED	NI:1	0204
33	6	R337 R338	270	55DEGC/+155DEGC, 0201, SMD	VISHAY	CRCW0201270RJNED	Nil	0201
				RESISTOR, THICK FILM, 0, -	NAANUUEA CTUBE	DESISTOR 0402 0		
	_	5465456		5%/+5%, 0.063W, 50V, -	MANUFACTURE	·		
34	2	R12 R472	0	55DEGC/+155DEGC, 0402, SMD	R SELECTION	5%_50V_0.063W_M_+/-200ppm	Nil	0402
				RESISTOR, THICK FILM, 100K, -				
	-	R25 R26 R341	4.5-1	5%/+5%, 0.05W, 30V, -	MANUFACTURE	/		0000
35	5	R535 R541	100k	55DEGC/+125DEGC, 0201, SMD	R SELECTION	5%_30V_0.05W_M_+/-200ppm	Nil	0201

			I	DECICTOR THICK FILM 20.4k	I			1
				RESISTOR, THICK FILM, 30.1k, -				
	_			1%/+1%, 0.063W, 50V, -				
36	1	R55	30.1k	55DEGC/+155DEGC, 0402, SMD	KOA SPEER	RK73H1ETTP3012F	Nil	0402
				RESISTOR, THICK FILM, 51k, -				
				1%/+1%, 0.063W, 50V, -	MANUFACTURE	·		
37	1	R56	51k	55DEGC/+155DEGC, 0402, SMD	R SELECTION	1%_50V_0.063W_M_+/-100ppm	Nil	0402
		R61 R321 R329						
		R330 R331 R332		RESISTOR, THICK FILM, 10K, -				
		R532 R533 R534		5%/+5%, 0.05W, 30V, -	MANUFACTURE	RESISTOR_0201_10k_+/-		
38	15	R537 R538 R548	10k	55DEGC/+125DEGC, 0201, SMD	R SELECTION	5%_30V_0.05W_M_+/-200ppm	Nil	0201
				RESISTOR, THICK FILM, 1Meg, -				
				1%/+1%, 0.063W, 50V, -	MANUFACTURE	RESISTOR_0402_1M_+/-		
39	1	R333	1Meg	55DEGC/+155DEGC, 0402, SMD	R SELECTION	1%_50V_0.063W_M_+/-100ppm	Nil	0402
				RESISTOR, THICK FILM, 4.7k, -				
				1%/+1%, 0.05W, 30V, -	MANUFACTURE	RESISTOR_0201_4.7k_+/-		
40	1	R339	4.7k	55DEGC/+155DEGC, 0201, SMD	R SELECTION	1%_30V_0.05W_M_+/-100ppm	Nil	0201
				RESISTOR, THICK FILM, 2.7k, -				
				1%/+1%, 0.05W, 30V, -	MANUFACTURE	RESISTOR_0201_2.7k_+/-		
41	1	R549	2.7k	55DEGC/+125DEGC, 0201, SMD	R SELECTION	1%_30V_0.05W_M_+/-100ppm	Nil	0201
				RESISTOR, METAL FILM, 0, -	MANUFACTURE			
42	3	R550 R551 R552	0	40DEGC/+85DEGC, 0402, SMD	R SELECTION	RESISTOR 0402 0	Nil	0201
				RESISTOR, THICK FILM, 100R, -				
				5%/+5%, 0.05W, 25V, -	MANUFACTURE	RESISTOR_0201_100_+/-		
43	1	R553	100	55DEGC/+125DEGC, 0201, SMD	R SELECTION	5%_25V_0.05W_M_+/-200ppm	Nil	0201
				SWITCH, TACT, 0.02A@15V,				
44	2	SW3 SW4	TL3700AF160Q	0.02A, 15V, SMD	E-SWITCH	TL3700AF160Q	Nil	
				, ,				
				IC, MICROPROCESSOR,				
				SIMPLELINK WI-FI AND INTERNET-				
				OF-THINGS SOLUTION, A SINGLE-				
			CC3200R1M2RG	•	TEXAS			
45	1	U1	С	3.6V, VQFN64, SMD	INSTRUMENTS	CC3200R1M2RGCR	Nil	VQFN64
				, , ,				

				IC, ANALOG, CUSTOM, CC26XX 5x5	TEXAS			
46	1	U2	CC26xx-5x5	DCDC, QFN32, SMD	INSTRUMENTS	ITEM_CC26XX_5X5_DCDC	Nil	QFN32
				IC, MEMORY, 2.5V SERIAL FLASH				
				MEMORY, 8Mb, 2.3V TO 3.6V,				
47	1	U3	W25X80ALZPIG	WSON8, SMD	WINBOND	W25X80ALZPIG	Nil	WSON8
				IC, MEMORY, 2M-BIT SERIAL				
				FLASH MEMORY, 2.3V TO 3.6V,				
48	1	U4	W25X20CLUXIG	USON8, SMD	WINBOND	W25X20CLUXIG	Nil	USON8
				IC, ANALOG, ULTRALOW-NOISE,				
				HIGH PSRR, FAST, RF, 1A LOW-				
				DROPOUT LINEAR REGULATORS,				
				VIN:2.7V TO 5.5V, VOUT:1.2V TO	TEXAS			
50	1	U7	TPS79601DR	5.5V, SON8, SMD	INSTRUMENTS	TPS79601DRBR	Nil	SON8
				IC, DIGITAL INTERFACE, SINGLE-				
				CHIP USB 2.0 TO DUAL UART				
51	1	U8	CP2104-F03-GM	BRIDGE, 3V TO 3.6V, QFN24, SMD	SILICON LABS	CP2104-F03-GM	Nil	QFN24
				CRYSTAL, RESONATOR, 32.768kHz,				
				-20PPM/+20PPM, -				
52	1	Y1	32.768kHz	40DEGC/+85DEGC, SMD	EPSON	FC-135 32.7680KA-AG0	Nil	
				CRYSTAL, CRYSTAL OSCILLATOR,				
				24MHz, -				
				15PPM/DEGC/+15PPM/DEGC, -				
53	1	Y2	24MHz	40DEGC/+85DEGC, SMD	EPSON	TSX-3225 24.0000MF15X-AC3	Nil	
				CRYSTAL, CRYSTAL OSCILLATOR,				
54	1	Y3	40MHz	40MHz, -40DEGC/+85DEGC, SMD	EPSON	FA-20H 40.0000MF20X-AJ3	Nil	
				CRYSTAL, OSCILATOR, 32.768kHz, -				
				20PPM/ + 20PPM, -40DEGC/				
55	1	Y4	32.768kHz	+85DEGC, 12.5pF, SMD	EPSON	FC-12M 32.7680KA-A3	Nil	

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